PREPARED BY:	DATE:	SPE . No. ED-96012			
a. musayama Feb. 6, 1996 SH		RP ISSUP, February 2, 1996			
APPROVED BY:	DATE:	PAGE			
N. Imanaka Feb. 1	ELECTRONIC CC GROUP SHARP	· · · · · · · · · · · · · · · · · · ·			
	SPECIFIC	CATION OPTO-ELECTRO'MC DEVICES DIV.			
	EVICE SPECIFICATION FOR				
	PHOTOTRIAC (COUPLER			
M	DDEL No, S21ME	28			
SHARP ta (1) This of Main • Con [• Me (2) Please is us • Uni • Tra • Oth (3) Please • Spa [• Nui Contact a devices for	easuring equipment • Tooling mach e take proper steps in order to maint ed for the uses mentioned below whi it concerning control and safety of a offic signal • Gas leak detection bre her safety equipment, etc. e do not use for the uses mentioned ace equipment • Telecommunication clear control equipment • Medical of a SHARP representative of sales office	used by improper use of the devices. nic equipment. ommunication equipment (Terminal) ine • AV equipment • Home appliance, etc. rain reliability and safety, in case this device ch require high reliability. vehicle (air plane, train, automobile etc.) aker • Fire box and burglar alarm box below which require extremely high reliability. n equipment (Trunk) 1			
CUSTOMER'S	APPROVAL	DATE PRESENTED BY			
DATE		T. Matsumura, Department General Manager of Engineering Dept. ,11 Opto-Electronic Devices Div.			
BY		ELECOM Group SHARP CORPORATION			

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ED-96012 MODEL No S2 MIES 1/8

1. Application

This specification applies to the outline and characteristics of phototriac coupler Model No. S21 ME8.

2. Outline

Refer to the attached drawing No. CY8238E02.

3. Ratings and characteristics

Refer to the attached sheet, page 4 to 6.

4. Reliability

Refer to the attached sheet, page 7.

5. Incoming inspection

Refer to the attached sheet, page 8.

6. Supplement

- 6.1 Isolation voltage shall be measured in the following method.
- (1) Short between pin 1, 2 and pin 3 on the primary side and between pin 4,5 and pin 6 on the secondary side.
- (2) The dielectric withstand tester with zero-cross circuit shall be used.
- (3) The wave form of the applied voltage shall be a sine wave.(It is recommended that the isolation voltage be measured in insulation oil.)
- 6.2 The business dealing name used for this product when ordered or delivered shall be S21ME8.
- 6.3 This product is not designed against irradiation.

This product is assembled with electrical input and output.

This product incorporates non-coherent light emitting diode.

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7. Notes

7.1 For cleaning

- (1) Solvent cleaning : Solvent temperature $45\degree$ or less Immersion for 3 min or less
- (2) Ultrasonic cleaning : The affect to device by ultrasonic cleaning is different by cleaning bath size, ultrasonic power output, cleaning time, PWB size or device mounting condition etc. Please test it in actual using condition and confirm that doesn't occur any defect before starting the ultrasonic cleaning.
- (3) Applicable solvent : Ethyl alcohol, Methyl alcohol Freon TE • TF, Diflon-solvent S3-E

Please refrain form using Chloro Fluoro Carbon type solvent to clean device as much as possible since it is internationally restricted to protect the ozonosphere. Before you use alternative solvent you are requested to confirm that it does not attack package resin.

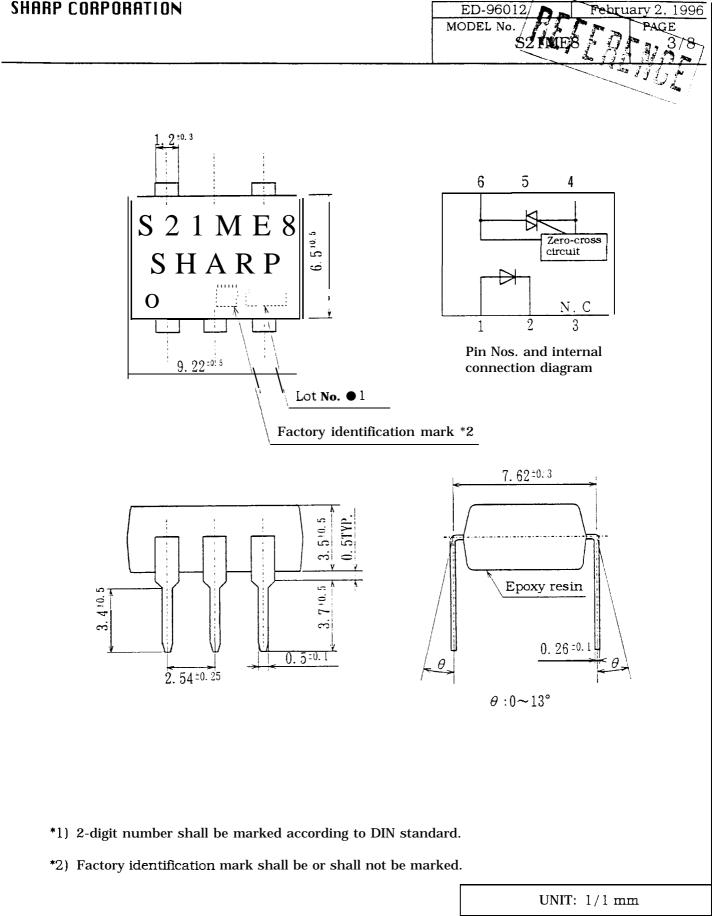
7.2 Usage

For triggering medium and power triac. (This model shall be used in the ON state condition of triggering power triac.)

- 7.3 If the voltage exceeding the repetitive peak off-state voltage (V_{DRM}) in the absolute maximum ratings is applied to the phototriac, it may cause not only faulty operation but breakdown. Make sure that the surge voltage exceeding V_{DRM} shall not be applied by using the varistor, CR.
- 7.4 The LED used in the Phototriac coupler generally decreases the light emission power by operation. Also, as this product is using high sensitive phototriac chip, please consider that miss-operation may be caused by too much forward current. In case of long operation time, please decide the input current which become
 2 -3 times of the Maximum value of the Minimum triggering current at circuit design with considering the degradation of the light emission power of the LED. (50% / 5years)
- 7.5 Precautions for Soldering Photocouplers

Refer to the attached sheet-1.

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UNIT: 1/1 mm				
Name	S21ME8 Outline Dimensions (Business dealing name : S21ME8)			
Drawing No.	CY8238E02			

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3.1 Absolute maximum ratings

Parameter		Symbol	Rating	unit
Innut	Forward current	IF	15	mA
Input	Reverse voltage	V _R	6	v
	RMS on-state current *1	Ι _Τ	0.1	Arms
output	Peak one cycle surge current	Isurge	1.2 (50Hz sine wave)	А
	Repetitive peak off-state voltage	V_{DRM}	800	v
Operating temperature		Topr	- 30 to +100	с
Storage temperature		Tstg	-55 to +125	ʻc
Isolation voltage *2		Viio	5.0	kVrms
Soldering temperature		Tsol	260 (For 10s)	ʻc

*1 The derating factors of absolute maximum rating due to ambient temperature are shown in Fig.1, 2.

*2 AC for rein, 40 to 60%RH. f=60Hz

3.2 Electrical characteristics

							Ta=25°C
	Parameter	symbol	MIN.	TYP.	MAX.	unit	Conditions
Input	Forward voltage	V _F	-	1.2	1.4	v	I _F =6mA
	Reverse current	I _R	-	-	10-5	А	V _R =3V
	Repetitive peak off-state current	I _{DRM}			10-6	Α	V _{DRM} =Rated
	On-state voltage	VT	-	1.7	3.0	v	I _T =0. 1A
output	Holding current	I _H	0.1	-	3.5	mA	V _D =6V
	Critical rate of rise of off-state voltage	dv/dt	500	-	-	V/μs	V_{DRM} = 1 / $\sqrt{2}$ · Rated
	Zero-cross voltage	Vox	-	-	20	v	R load, I _F =6mA
Transfer	Minimum trigger current	I _{FT}	-	-	3.0	mA	$V_{\rm D}=6V$ $R_{\rm L}=100\Omega$
tics	Isolation resistance	Riso	5×10 ¹⁰	10"	-	Ω	DC500V 40 to 60%RH
	Turn on time	t _{ON}			50	μs	$V_D = 6V, R_L = 100 \Omega$ $I_F = 6mA$

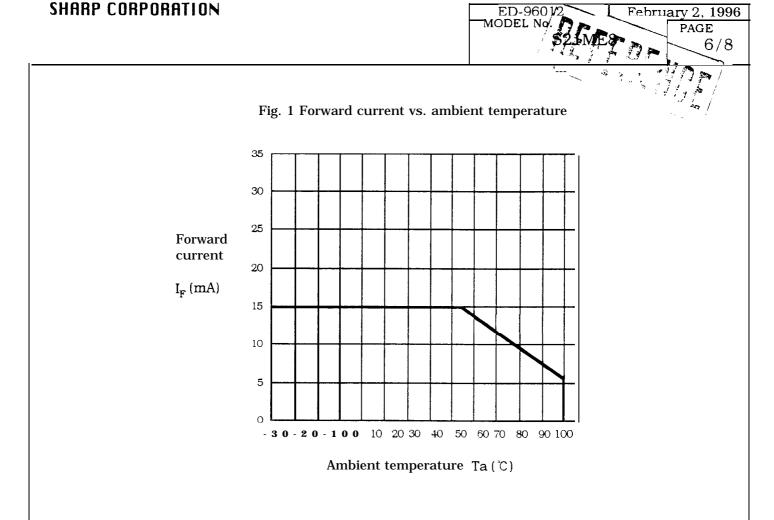
Ta=25℃

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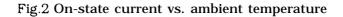
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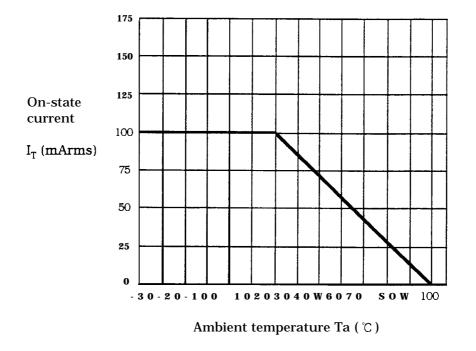
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4. Reliability

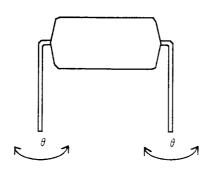
The reliability of products shall be satisfied with items listed below.

Confidence level : 90% LTPD : 10%/20%

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Test Items	Test Conditions *1	Failure Judgement Criteria	Samples (n) Defective(C)	
Solderability *2	230℃, 5 s		n=11, C=0	
Soldering heat *3	260℃,10 s		n=11.C=O	
Terminal strength (Tension)	Weight : 5.0N 5 s/each terminal	$V_F > U \times 1.2$	n=11. C=0	
Terminal strength (Bending) *4	Weight : 2.5N 2 times/each terminal	VT> U×1.2	n=11. C=0	
Mechanical shock	$\frac{15000 \text{m/s}^2, 0.5 \text{ms}}{3 \text{ times}/ \pm X, \pm Y, \pm Z \text{ direction}}$	$I_{\rm FT} > U \times 1.3$ $I_{\rm R} > U \times 2.0$	n=11.C=O	
Variable frequency vibration	100 to 2000 to 100Hz/4min 200m/s ² 4 times/ X, Y, Z direction	I _{DRM} >U×2.0	n=11, C=0	
Temperature cycling	1 cycle -55 ℃ to +125℃ (30min) (30min) 20 cycles test, Without Road	T . Luna	n=22,C=0	
High temp. and high humidity storage	+60℃, 90%RH,1000h	U : Upper specification limit	n=22,C=0	
High temp. storage	+125°C, 1000h	L : Lower	n=22 ,C=0	
Low temp. storage	-55°C, 1000h	specification limit	n=22,C=0	
Operation life	I _F =15mA, I _T =100mA Ta=25°C, 1000h		n=22,C=0	

- *1 Test method, conforms to JIS C 7021.
- *2 Solder shall adhere at the area of 95% or more of immersed portion of lead and pin hole or other holes shall not be concentrated on one portion.
- *3 Dip into the position of 1.0mm from the resin part.
- *4 Terminal bending direction is shown below.



- 5. Incoming inspection
 - 5.1 Inspection items
 - (1) Electrical characteristics

 V_{F} , I_{R} , I_{DRM} , V_{T} , I_{FT} , Riso, Viso

(2) Appearance

5.2 Sampling method and Inspection level

A single sampling plan, normal inspection level II based on 1S0 2859 is applied. The AQL according to the inspection items are shown below.

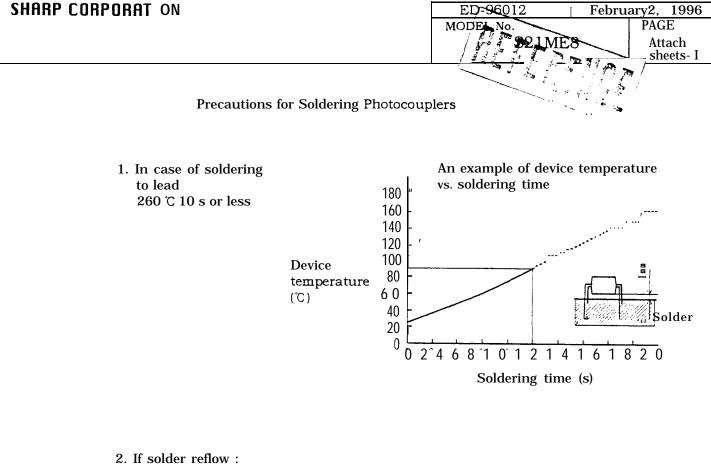
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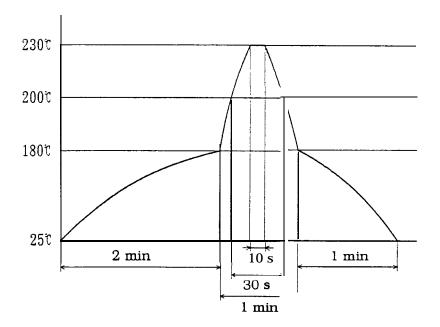
Defect	Inspection item	AQL (%)
Major defect	Electrical characteristics Unreadable marking	0.1
Minor defect	Appearance defect except the above mentioned.	0.4

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It is recommended that only one soldering be done at the temperature and the time within the temperature profile as shown in the figure.



3. Other precautions

An infrared lamp used to heat up for soldering may cause a localized temperature rise in the resin. So keep the package temperature within that specified in Item 2. Also avoid immersing the resin part in the solder.